# onsemi

# **MOSFET** - Power, Single N-Channel, SUPERFET<sup>®</sup> V, Easy Drive, TO247-3L 600 V, 99 mΩ, 33 A

## NTHL099N60S5

#### Description

SUPERFET V MOSFET Easy Drive series combines excellent switching performance without sacrificing ease of use and EMI issues for both hard and soft switching topologies.

#### Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. R<sub>DS(on)</sub> = 79.2 mΩ
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### Applications

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

#### ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub> = $25^{\circ}$ C, Unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	V <sub>DSS</sub>	600	V	
Gate-to-Source Voltage	Gate-to-Source Voltage DC		±30	V
	AC (f > 1 Hz)		±30	
Continuous Drain Current	Continuous Drain Current $T_{C} = 25^{\circ}C$		33*	А
	$T_{C} = 100^{\circ}C$		20*	
Power Dissipation	Power Dissipation $T_{C} = 25^{\circ}C$		184	W
Pulsed Drain Current (Note 1)	Pulsed Drain Current (Note 1) $T_C = 25^{\circ}C$		95*	А
Pulsed Source Current (Body Diode) (Note 1) $T_C = 25^{\circ}C$		I <sub>SM</sub>	95*	A
Operating Junction and Storage Range	T <sub>J</sub> , T <sub>STG</sub>	–55 to +150	°C	
Source Current (Body Diode)		I <sub>S</sub>	33*	А
		E <sub>AS</sub>	232	mJ
Avalanche Current	I <sub>AS</sub>	5.1	А	
Repetitive Avalanche Energy (N	E <sub>AR</sub>	1.84	mJ	
MOSFET dv/dt	dv/dt	120	V/ns	
Peak Diode Recovery dv/dt (No		50		
Lead Temperature for Soldering (1/8" from case for 10 seconds)	ΤL	260	°C	

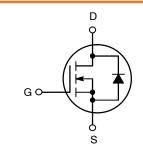
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. \*Drain current limited by maximum junction temperature.

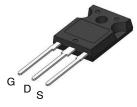
1. Repetitive rating: pulse-width limited by maximum junction temperature.

2.  $I_{SD} \le 13.5$  A, di/dt  $\le 200$  A/µs,  $V_{DD} \le 400$  V, starting  $T_J = 25^{\circ}$ C.

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Α	gust, 2021 – Rev. 2	v. 2	

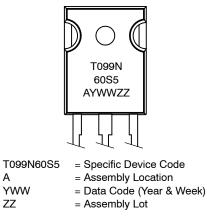
V <sub>DSS</sub> R <sub>DS(ON)</sub> MAX		I <sub>D</sub> MAX
600 V	99 mΩ @ 10 V	33 A





TO-247 Long Leads CASE 340CX

#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

Device	Package	Shipping
NTHL099N60S5	TO-247	30 Units / Tube

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#### THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ ext{ heta}JC}$	0.68	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{ hetaJA}$	40	

#### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•			•	4
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C	600	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	$I_D$ = 10 mA, Referenced to 25°C	_	630	-	mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 600 V, $T_J$ = 25 $^\circ C$	_	-	1	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS}$ = ±30 V, $V_{DS}$ = 0 V	_	-	±100	nA
ON CHARACTERISTICS	•	•				
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS}$ = 10 V, $I_D$ = 13.5 A, $T_J$ = 25 $^\circ C$	_	79.2	99	mΩ
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{GS}$ = $V_{DS}$ , $I_D$ = 2.8 mA, $T_J$ = 25°C	2.4	-	4.0	V
Forward Trans-conductance	9fs	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 13.5 \text{ A}$	-	26	-	S
CHARGES, CAPACITANCES & GATE	RESISTANCE	•			•	
Input Capacitance	C <sub>ISS</sub>	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 250 kHz	-	2500	-	pF
Output Capacitance	C <sub>OSS</sub>			41	-	1
Time Related Output Capacitance	C <sub>OSS(tr.)</sub>			642	-	
Energy Related Output Capacitance	C <sub>OSS(er.)</sub>	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	_	70	-	
Total Gate Charge	Q <sub>G(tot)</sub>	$V_{DD}$ = 400 V, I <sub>D</sub> = 13.5 A, V <sub>GS</sub> = 10 V	_	48	-	nC
Gate-to-Source Charge	Q <sub>GS</sub>		_	12	-	
Gate-to-Drain Charge	Q <sub>GD</sub>		_	14	-	
Gate Resistance	R <sub>G</sub>	f = 1 MHz	-	6.9	-	Ω
SWITCHING CHARACTERISTICS		•				
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	26	-	ns
Rise Time	t <sub>r</sub>	l <sub>D</sub> = 13.5 A, R <sub>G</sub> = 4.7 Ω	-	17	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	1	-	92	-	
Fall Time	t <sub>f</sub>	1	-	4.2	-	
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS			•	•	•
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS}$ = 0 V, $I_{SD}$ = 13.5 A, $T_{J}$ = 25°C	-	-	1.2	V

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

t<sub>RR</sub>

 $Q_{RR}$ 

 $\begin{array}{l} V_{GS} = 0 \,\, V, \, I_{SD} = 13.5 \,\, A, \\ dI/dt = 100 \,\, A/\mu s, \, V_{DD} = 400 \,\, V \end{array}$ 

310

4627

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ns

nC

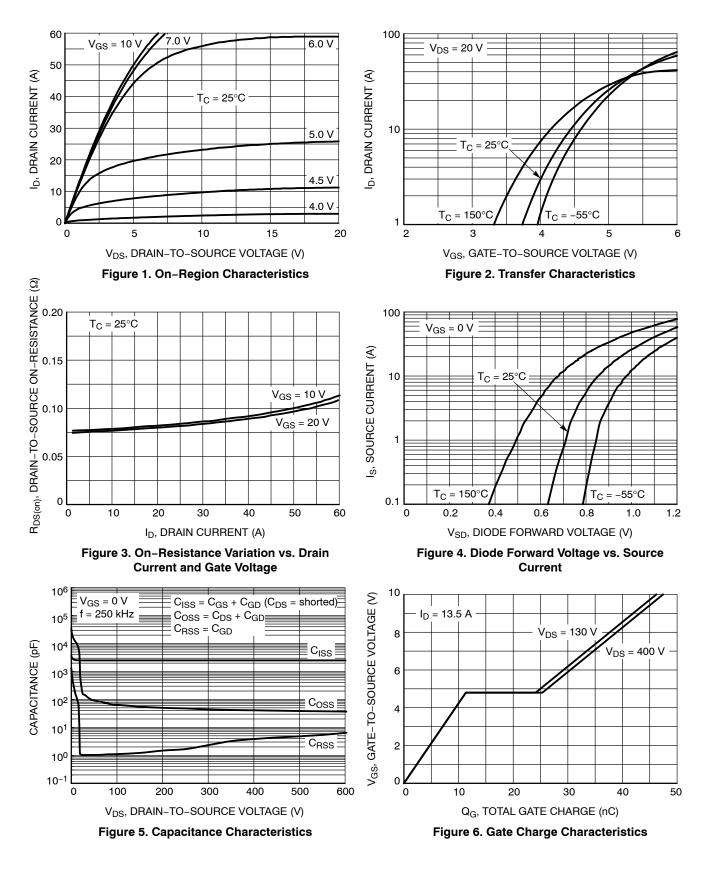
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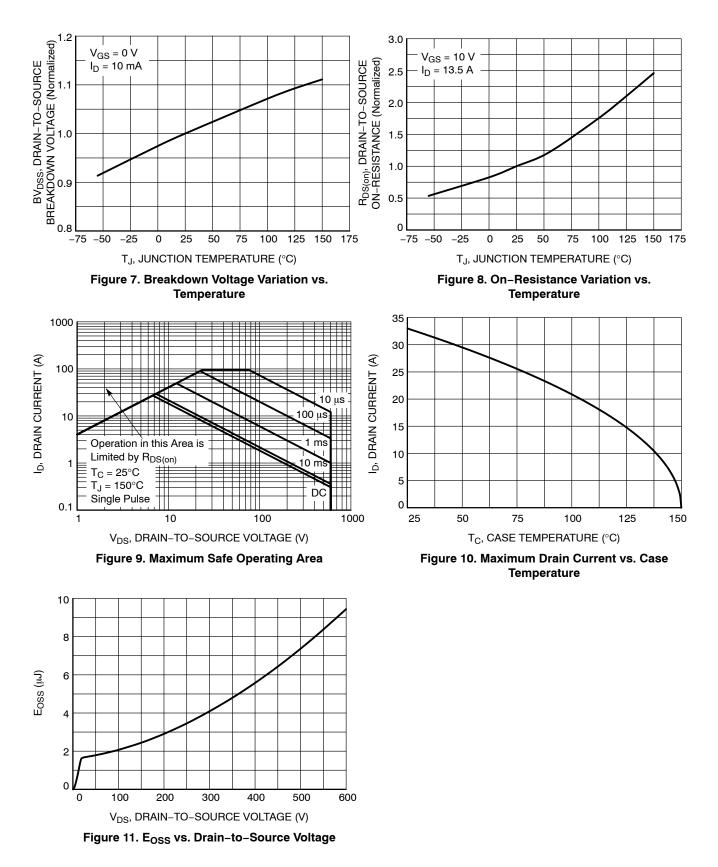
**Reverse Recovery Time** 

Reverse Recovery Charge

#### **TYPICAL CHARACTERISTICS**



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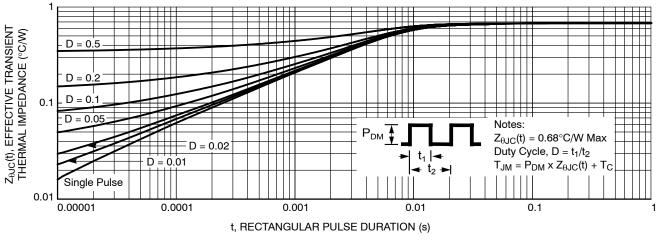


Figure 12. Transient Thermal Impedance

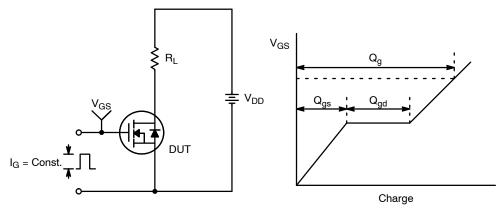


Figure 13. Gate Charge Test Circuit & Waveform

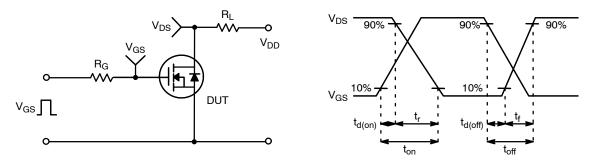


Figure 14. Resistive Switching Test Circuit & Waveforms

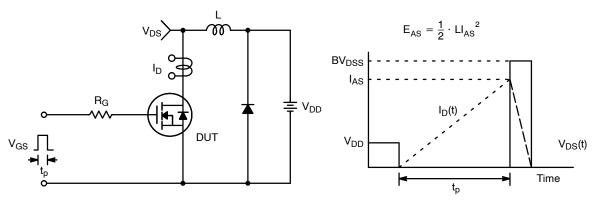


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

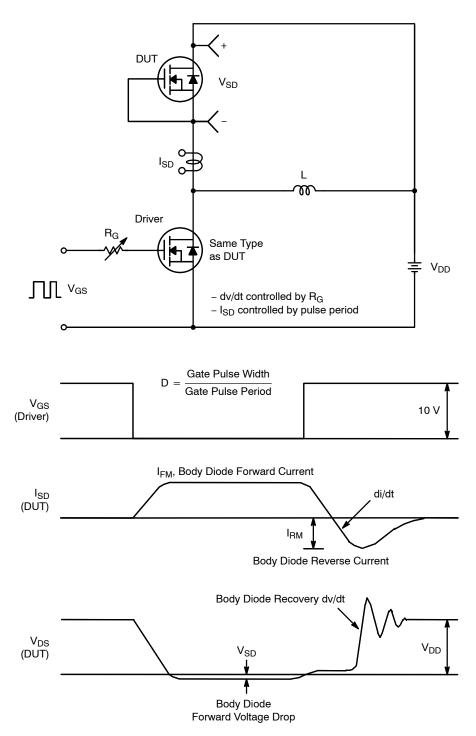
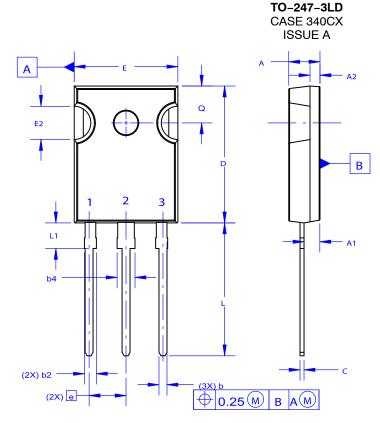


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

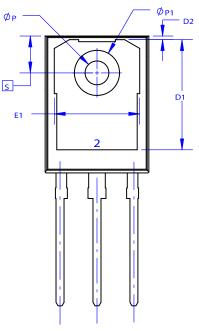
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#### **PACKAGE DIMENSIONS**



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
  D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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